Appl. No. 10/722,365 Amdt. Dated March 1, 2005 Reply to Office Action of December 1, 2004

## Amendments to the Specification

Please replace paragraph [0061] with the following amended paragraph: (Second Embodiment)

FIGs. 7(A) to 8 illustrate a method of manufacturing a semiconductor device (e.g. an optical deice device) according to a second embodiment of the present invention. FIG. 8 is a plan view of a cover 120 and the semiconductor substrate 20 facing each other.